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artment of Commerce & Trademark Office	
Docket No. <u>P7443-9010</u>	78
June 9, 1999	300
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof		
1. Name of conveying party(ies) (1) Hiroyuki MAKINO; (2) Masaru TANAKA; (3) Kiyoshi AWAI; (4) Toshiyuki SAKEMI Additional name(s) of conveying party(ies) attached? Yes XX No 3. Nature of conveyance: XX Assignment Merger Security Agreement Change of Name Other Execution Date: (1)&(3) 6/4/99; (2)&(4) 6/2/99	2. Name and address of receiving party(ies): Name:SUMITOMO HEAVY INDUSTRIES, LTD. Internal Address: Street Address:9-11, Kitashinagawa 5-chome,Shinagawa-ku, Tokyo 141-8686, Japan City:State:Zip: Additional name(s) & address(es) attached?YesXX No	
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: (1)&(3) 6/4/99: (2)&(4) 6/2/99 A. Patent Application No.(s) New Application Additional numbers attached?Yes XX No		
5. Name and address of party to whom correspondence concerning document should be mailed: Name: NIKAIDO, MARMELSTEIN, MURRAY & ORAM Internal Address: Street Address: Metropolitan Square, 655 15th St., N.W., Suite 330 - G Street Lobby City: Washington State: DC Zip: 20005-5701 02/22/1994 #60906k 00000028 14/660 09028413	6. Total number of applications and patents involved:	
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. David T. Nikaido Name of Person Signing Reg. No. 22,663 Total number of pages including cover sheet, attachments and document: 2		

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by SUMITOMO HEAVY INDUSTRIES, LTD. 9-11, Kitashinagawa 5-chome, Shinagawa-ku, Tokyo 141-8686 (hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled FILM DEPOSITION METHOD FOR FORMING COPPER FILM for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below: *filed on _____, Serial No. ___ (Nikaido, Marmelstein, Murray & Oram is hereby authorized to insert the serial code, serial number and/or filing date hereon, when known) and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted. The ASSIGNOR agrees to execute all papers necessary in connection with application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient. The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, division, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding. IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s). June 4, 1999 Hiroyuki MAKINO 7-iroyuki Makino (SIGNATURE) (TYPE NAME) (DATE) Masaru TANAKA June 2, 1999 (TYPE NAME) (DATE) Kiyoshi AWAI June 4, 1999 (TYPE NAME) (DATE) June 2, 1999 Toshiyuki SAKEMI (TYPE NAME) (DATE) (SIGNATURE) (TYPE NAME) (DATE) (SIGNATURE) (TYPE NAME) (DATE) (SIGNATURE) (TYPE NAME) (DATE) (SIGNATURE)

NO LEGALIZATION REQUIRED

PATENT REEL: 010038 FRAME: 0106

TO DECITED IT

RECORDED: 06/09/1999

[Insert

[Title of Invention]

filing of the application, this

completed]

section must be

[Signature(s)]

[*If the assignment is being filed after the

ASSIGNEE's Name(s) Address(es)]